



Semiconductor Device Type: J7A 006 VDFN 2.0x2.5mm NiPdAu			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)			J-STD-609A Product Marking and/or Pkg. Labeling e4		
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	5.03	(mg) Total	Mold Compound	% of Total Weight	40.24	
Silica Fused	60676-86-0	Mold Compound	37.222	4.653	372.220		Silica Fused	60676-86-0	92.50		
Epoxy Resin	Trade secret	Mold Compound	1.408	0.176	14.084		Epoxy Resin	Trade secret	3.50		
Phenol Resin	Trade secret	Mold Compound	1.408	0.176	14.084		Phenol Resin	Trade secret	3.50		
Carbon Black	1333-86-4	Mold Compound	0.201	0.025	2.012		Carbon Black	1333-86-4	0.50		
Copper	7440-50-8	Lead Frame	46.488	5.811	464.875		Total 100.00				
Iron	7439-89-6	Lead Frame	0.070	0.009	699	5.82	(mg) Total	Lead Frame	% of Total Weight	46.59	
Phosphorous	7723-14-0	Lead Frame	0.019	0.002	186		Copper	7440-50-8	99.78		
Zinc (Metal)	7440-66-6	Lead Frame	0.014	0.002	140		Iron	7439-89-6	0.15		
Silver	7440-22-4	Die Attach	0.754	0.094	7,540		Phosphorous	7723-14-0	0.04		
Silica Fused	60676-86-0	Die Attach	0.657	0.082	6,574		Zinc (Metal)	7440-66-6	0.03		
Epoxy Resin	120206-26-0	Die Attach	0.440	0.055	4,404		Total 100.00				
Poly(Bisphenol A-co-epichlorohydrin)	25068-38-6	Die Attach	0.148	0.019	1,482	0.25	(mg) Total	Die Attach	% of Total Weight	2.00	
Silicon	7440-21-3	Chip (Die)	9.170	1.146	91,700		Silver	7440-22-4	37.70		
Gold	7440-57-5	Wire Bond	0.750	0.094	7,500		Silica Fused	60676-86-0	32.87		
Nickel	7440-02-0	Plating on external leads (pins)	1.125	0.141	11,250		Epoxy Resin	120206-26-0	22.02		
Palladium	7440-05-3	Plating on external leads (pins)	0.063	0.008	625		Poly(Bisphenol A-co-epichlorohydrin)	25068-38-6	7.41		
Gold	7440-57-5	Plating on external leads (pins)	0.063	0.008	625		Total 100.00				
0.0125 g Total Mass			TOTALS:	100.000	12.500	1,000,000	1.15	Total (mg)	Chip (Die)	% of Total Weight	9.17
						Dual	Doped Silicon	7440-21-3	100.00		
						Total 100.00					
						0.09	(mg) Total	Wire Bond	% of Total Weight	0.75	
							Gold	7440-57-5	100.00		
						Total 100.00					
						0.16	(mg) Total	Plating on external leads (pins)	% of Total Weight	1.25	
							Nickel	7440-02-0	90.00		
							Palladium	7440-05-3	5.00		
							Gold	7440-57-5	5.00		
						Total 100.00					

This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero)

Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and/or analytical test data.

If a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology Incorporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is not below the threshold of regulatory concern for any regulatory scheme world-wide.

Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL iQTM family of databases to obtain a test report at <http://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/>

The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and certain "reels" may be made from PVC plastic.

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Assembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at <http://echa.europa.eu/web/guest/candidate-list-table>

12.50

100.00